

安靠封装测试(上海)有限公司(ATC) 是安靠在中国的全资子公司。公司成立于2001年, 拥有包括晶圆针测, 封装, 终测和物流配送在内的全套半导体后段解决方案。测试能力涵盖逻辑测试, 混合信号测试和存储器件测试。安靠在中国本地拥有强大的技术和客户支持团队, 为客户提供最完美的服务。

ATC – 安靠(中国)



安靠(中国)位于上海外高桥保税园区, 紧临中国主要晶圆代工厂群。客户可以通过“外高桥物流保税园区”以保税或完税方式将货物快速便捷地送抵国内最终用户。



安靠(中国) 提供的封装形式有:

TSOP, *MicroLeadFrame*[®], *ChipArray*[®], Flip Chip BGA, PBGA, *Stacked CSP*, Stacked TSOP, Memory Card Modules.

安靠(中国)工厂概况:

- 约2000名雇员
- 工厂已获得 ISO-9001和 ISO-14001, ISO18000, ISO TS-16949:2002认证



TSOP I



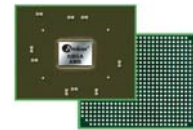
MicroLeadFrame[®]



PBGA



ChipArray[®]



Flip Chip BGA



Memory Card Modules



Stacked CSP

Amkor Assembly & Test (Shanghai) Co., Ltd. (ATC) is a wholly-owned subsidiary of Amkor Technology, Inc. ATC commenced operations in 2001 and currently offers full turnkey assembly and test services including wafer probe, assembly, final test and drop ship. Our test capabilities include logic, mixed signal and memory devices. Amkor has assembled strong local engineering and customer support teams to provide complete customer satisfaction.

ATC – Amkor Technology China



ATC is located in the Waigaoqiao Free Trade Zone, Pudong, Shanghai, near the major Chinese foundries. ATC’s customers benefit from direct access to a new ‘Bonded Logistic Park’ which enables VAT and Bonded product transfers to their domestic customers.



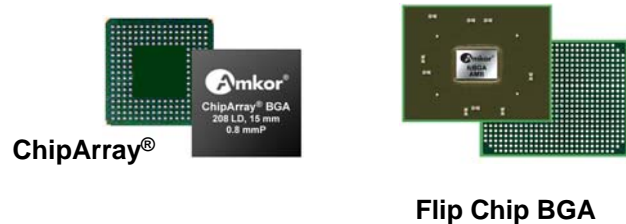
ATC Product Offering:

TSOP, *MicroLeadFrame*[®], *ChipArray*[®], Flip Chip BGA, PBGA, *Stacked CSP*, *Stacked TSOP*, Memory Card Modules.



ATC Factories:

- More than 2000 employees
- ISO-9001, ISO-14001, ISO-18000, ISO TS-16949:2002 certified



Memory Card Modules



Stacked CSP

For questions, please e-mail marketing@amkor.com